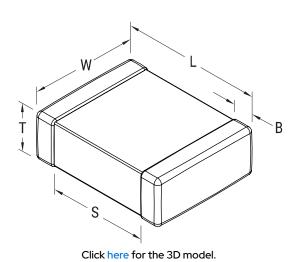




SMD Comm X8G HT150C, Ceramic, 0.033 uF, 2%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	130 mg
Shelf Life	78 Weeks
MSL	1

0.033 uF

30.303 GOhms

Dimensions	
Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.6mm +/-0.35mm

5.7mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
5mm +/-0.4mm	Tolerance	2%
1mm +/-0.15mm	Voltage DC	50 VDC
3.5mm MIN	Dielectric Withstanding Voltage	125 VDC
0.6mm +/-0.35mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
4000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

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